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FDC6331L

Integrated Load Switch

General Description

This device is particularly suited for compact power management in portable electronic equipment where 2.5V to 8V input and 2.8A output current capability are needed. This load switch integrates a small N-Channel power MOSFET (Q1) that drives a large P-Channel power MOSFET (Q2) in one tiny SuperSOT™-6 package.

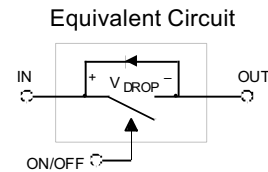
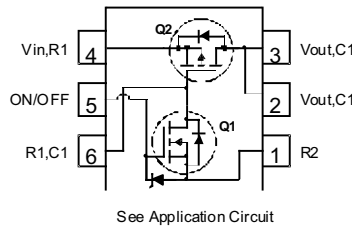
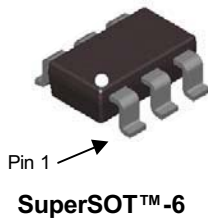
Applications

- Load switch
- Power management



Features

- -2.8 A, -8 V. $R_{DS(ON)} = 55\text{ m}\Omega @ V_{GS} = -4.5\text{ V}$
 $R_{DS(ON)} = 70\text{ m}\Omega @ V_{GS} = -2.5\text{ V}$
 $R_{DS(ON)} = 100\text{ m}\Omega @ V_{GS} = -1.8\text{ V}$
- Control MOSFET (Q1) includes Zener protection for ESD ruggedness (>6KV Human body model)
- High performance trench technology for extremely low $R_{DS(ON)}$



Absolute Maximum Ratings T_A=25°C unless otherwise noted

Symbol	Parameter	Ratings	Units
V _{IN}	Maximum Input Voltage	± 8	V
V _{ON/OFF}	High level ON/OFF voltage range	-0.5 to 8	V
I _{Load}	Load Current – Continuous (Note 1)	2.8	A
	– Pulsed	9	
P _D	Maximum Power Dissipation (Note 1)	0.7	W
T _J , T _{STG}	Operating and Storage Junction Temperature Range	-55 to +150	°C

Thermal Characteristics

R _{θJA}	Thermal Resistance, Junction-to-Ambient (Note 1)	180	°C/W
R _{θJC}	Thermal Resistance, Junction-to-Case (Note 1)	60	°C/W

Package Marking and Ordering Information

Device Marking	Device	Reel Size	Tape width	Quantity
.331	FDC6331L	7"	8mm	3000 units

Electrical Characteristics

$T_A = 25^\circ\text{C}$ unless otherwise noted

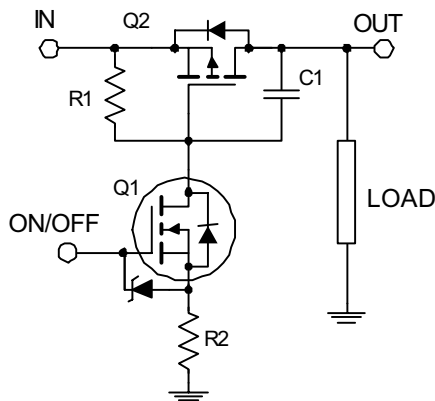
Symbol	Parameter	Test Conditions	Min	Typ	Max	Units
Off Characteristics						
BV_{IN}	Vin Breakdown Voltage	$V_{ON/OFF} = 0\text{ V}$, $I_D = -250\ \mu\text{A}$	8			V
I_{Load}	Zero Gate Voltage Drain Current	$V_{IN} = 6.4\text{ V}$, $V_{ON/OFF} = 0\text{ V}$			-1	μA
I_{FL}	Leakage Current, Forward	$V_{ON/OFF} = 0\text{ V}$, $V_{IN} = 8\text{ V}$			-100	nA
I_{RL}	Leakage Current, Reverse	$V_{ON/OFF} = 0\text{ V}$, $V_{IN} = -8\text{ V}$			100	nA
On Characteristics (Note 2)						
$V_{ON/OFF(th)}$	Gate Threshold Voltage	$V_{IN} = V_{ON/OFF}$, $I_D = -250\ \mu\text{A}$	0.4	0.9	1.5	V
$R_{DS(on)}$	Static Drain-Source On-Resistance (Q2)	$V_{GS} = -4.5\text{ V}$, $I_D = -2.8\text{ A}$ $V_{GS} = -2.5\text{ V}$, $I_D = -2.5\text{ A}$ $V_{GS} = -1.8\text{ V}$, $I_D = -2.0\text{ A}$		34 45 64	55 70 100	m Ω
$R_{DS(on)}$	Static Drain-Source On-Resistance (Q1)	$V_{GS} = 4.5\text{ V}$, $I_D = 0.4\text{ A}$ $V_{GS} = 2.7\text{ V}$, $I_D = 0.2\text{ A}$		3.1 3.8	4 5	Ω
Drain-Source Diode Characteristics and Maximum Ratings						
I_S	Maximum Continuous Drain-Source Diode Forward Current				-0.6	A
V_{SD}	Drain-Source Diode Forward Voltage	$V_{ON/OFF} = 0\text{ V}$, $I_S = -0.6\text{ A}$ (Note 2)			-1.2	V

Notes:

1. $R_{\theta JA}$ is the sum of the junction-to-case and case-to-ambient thermal resistance where the case thermal reference is defined as the solder mounting surface of the drain pins. $R_{\theta JC}$ is guaranteed by design while $R_{\theta JA}$ is determined by the user's board design.

2. Pulse Test: Pulse Width < 300 μs , Duty Cycle < 2.0%.

FDC6331L Load Switch Application Circuit



External Component Recommendation:

For additional in-rush current control, R2 and C1 can be added. For more information, see application note AN1030.

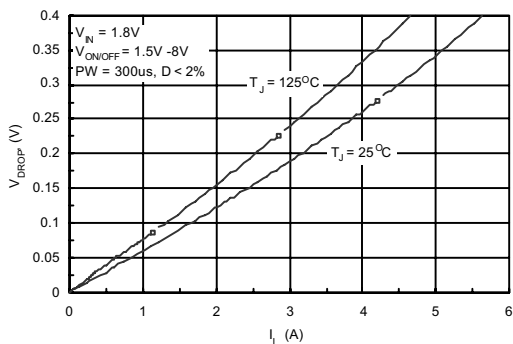


Figure 1. Conduction Voltage Drop Variation with Load Current.

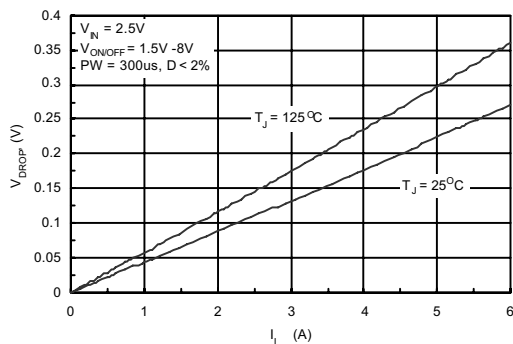


Figure 2. Conduction Voltage Drop Variation with Load Current.

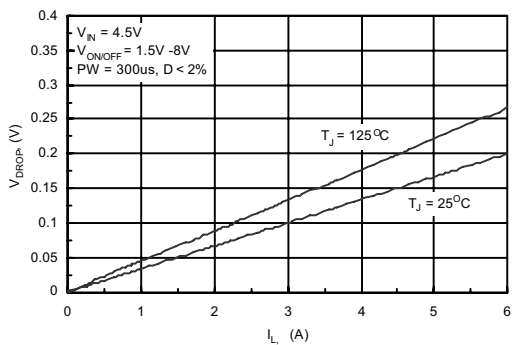


Figure 3. Conduction Voltage Drop Variation with Load Current.

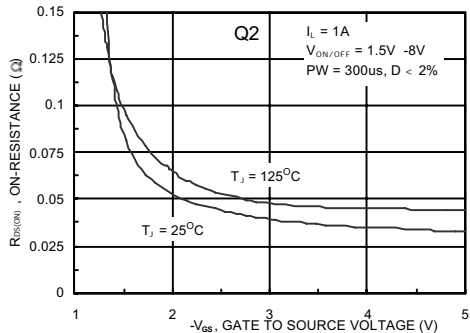


Figure 4. On-Resistance Variation With Input Voltage

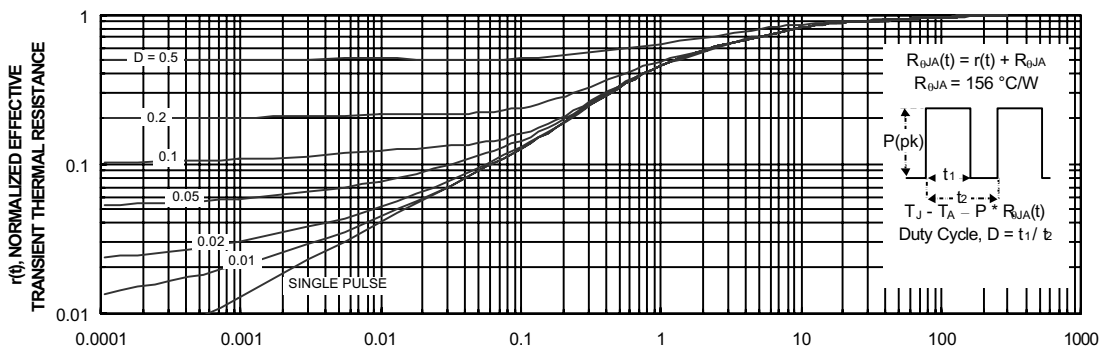



Figure 5. Transient Thermal Response Curve.

Thermal characterization performed on the conditions described in Note 2. Transient thermal response will change depends on the circuit board design.



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